

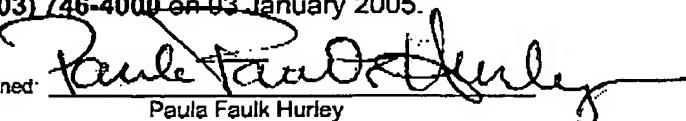
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ATTORNEY DOCKET: CPAC 1017-4 D2

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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of: Marcos Karnezos

Attorney Docket No.: CPAC 1017-4 D2

Application No.: 10/632,551

Examiner: Jasmine Clark

Filed: 02 August 2003

Group: 2811

Title: Semiconductor Multi-Package
Module Having Wirc Bond Interconnect
Between Stacked Packages And Having
Electrical Shicld

Confirmation No.: 2571

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Sir:

Applicants submit the below-listed documents to be placed in the file:

- Takiar et al.; U.S. Patent No. 5,495,398 issued 27 February 1996 for "Stacked Multi-Chip Modules and Method of Manufacturing".
- Chen et al.; U.S. Patent No. 6,472,741 issued 29 October 2002 for "Thermally-Enhanced Stacked-Die Ball Grid Array Semiconductor Package and Method of Fabricating Same".
- Kondo et al.; U.S. Patent No. 6,545,365 issued 08 April 2003 for "Resin-Sealed Stacked Chip Type Semiconductor Device".

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- Ichikawa; U.S. Patent No. 6,593,647 issued 15 July 2003 for "Semiconductor Device".

Respectfully submitted,

Bill Kennedy, Reg. No. 33,407

Date: 03 January 2005

HAYNES BEFFEL & WOLFELD LLP
P.O. Box 366
Half Moon Bay, CA 94019
(650) 712-0340 (telephone)
(650) 712-0263 (facsimile)
BK:pfh

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